

Welcome to **E-XFL.COM**

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	19700
Total RAM Bits	434176
Number of I/O	360
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec20e-4f484c

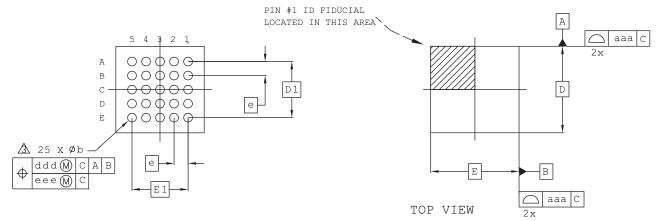
Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

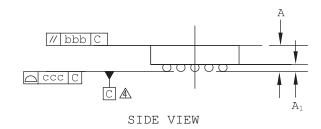


25-Ball WLCS Package (0.40 mm Pitch)

Dimensions in Millimeters



BOTTOM VIEW



Notes:

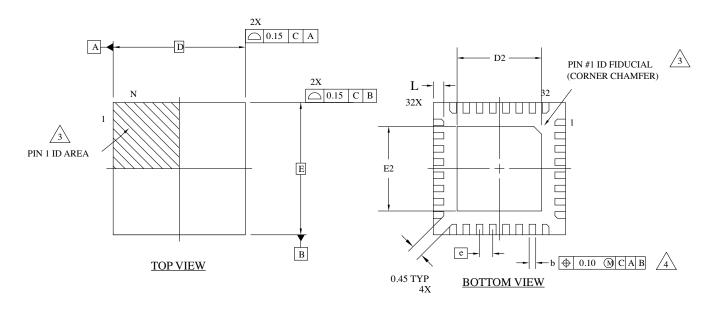
- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- A PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

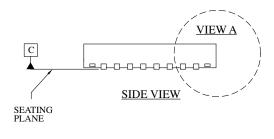
REF.	Min.	Nom.	Max.
A	0.535	0.575	0.615
A1	0.170	0.200	0.230
b	0.220	0.250	0.280
D	2	.492 BS	SC
E	2	.546 BS	SC
D1	1	.60 BSC	
E1	1	.60 BSC	
е	0.40 BSC		
aaa	0.025		
bbb	0.060		
ccc	0.015		
ddd	0.150		
eee	0	.050	

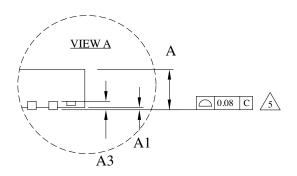


32-Pin QFN Package Option 2: MachXO2™

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

DIMENSION 6 APPLIES TO PLATED
TERMINAL AND IS MEASURED BETWEEN
0.15 AND 0.30 mm FROM TERMINAL TIP.

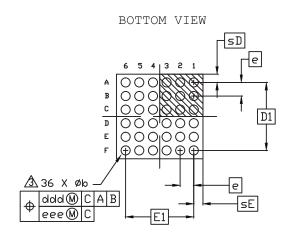
APPLIES TO EXPOSED PORTION OF TERMINALS.

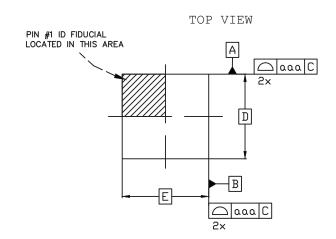
SYMBOL MIN. NOM. MAX. A 0.50 0.55 0.60 A1 0.00 0.02 0.05 A3 0.2 REF D 5.0 BSC D2 3.10 3.20 3.30 E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC L 0.35 0.40 0.45				
A1 0.00 0.02 0.05 A3 0.2 REF D 5.0 BSC D2 3.10 3.20 3.30 E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	SYMBOL	MIN.	NOM.	MAX.
A3 0.2 REF D 5.0 BSC D2 3.10 3.20 3.30 E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	A	0.50	0.55	0.60
D 5.0 BSC D2 3.10 3.20 3.30 E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	A1	0.00	0.02	0.05
D2 3.10 3.20 3.30 E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	A3		0.2 REF	
E 5.0 BSC E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	D	5.0 BSC		
E2 3.10 3.20 3.30 b 0.20 0.25 0.30 e 0.50 BSC	D2	3.10	3.20	3.30
b 0.20 0.25 0.30 e 0.50 BSC	Е	5.0 BSC		
e 0.50 BSC	E2	3.10	3.20	3.30
	b	0.20	0.25	0.30
L 0.35 0.40 0.45	e	0.50 BSC		
	L	0.35	0.40	0.45

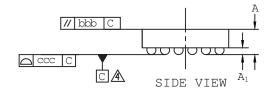


36-Ball WLCS Package Option 2: MachXO3[™]

Dimensions in Millimeters







NOTES:

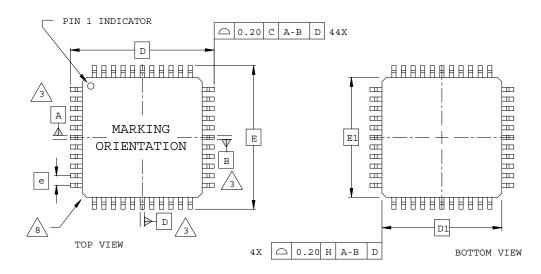
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM [C].
- \triangle PRIMARY DATUM $\boxed{\text{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

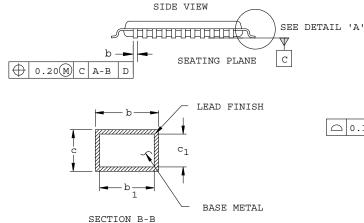
REF.	Min.	Nom.	Max.
A	0.510	0.543	0.576
A1	0.167	0.196	0.225
b	0.239	0.266	0.319
D		2.487 BS	C
E		2.541 BS	C
D1		2.00 BSC	:
E1		2.00 BSC	;
е		0.40 BSC	:
sD	ı	0.244	1
sE	- 0.271		-
aaa	0.025		
bbb	0.060		
ccc	0.030		
ddd	0.0150		
eee		0.050	

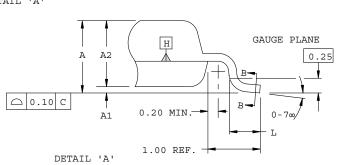


44-Pin TQFP Package (1.4 mm thick)

Dimensions in Millimeters







NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\stackrel{\textstyle >}{\scriptstyle 3}$ datums a, b and d to be determined at datum plane H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

/8\ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

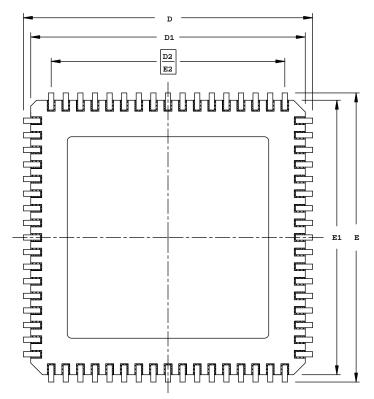
SYMBOL	MIN.	NOM.	MAX.
A	=	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D		12.00 BSC	
D1		10.00 BSC	
E		12.00 BSC	
E1		10.00 BSC	
L	0.45	0.60	0.75
N		44	
е		0.80 BSC	
b	0.30	0.37	0.45
b1	0.30	0.35	0.40
С	0.09	0.15	0.20
c1	0.09	0.13	0.16

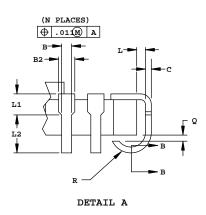


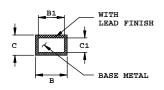
68-Pin JLCC Package

Dimensions in Inches

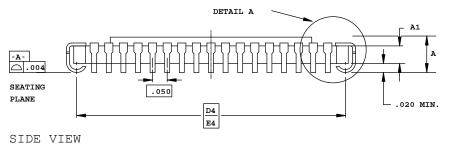
BOTTOM VIEW







SECTION B-B



NOTES:

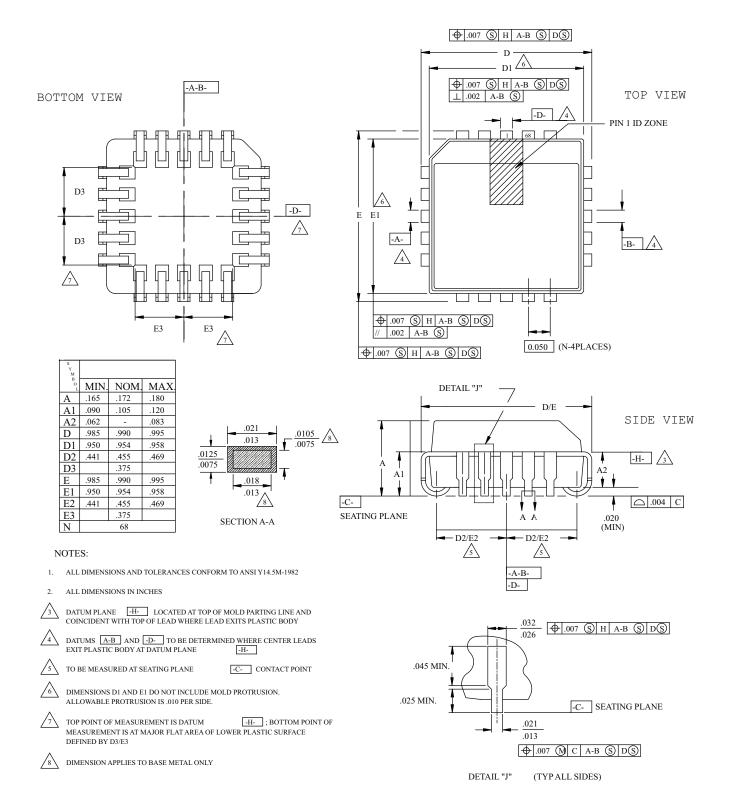
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- 3. CORNER CHAMFERS AND/OR NOTCHES ARE OPTIONAL.

S M B O L	INCHES		
o r	MIN.		MAX.
A	.115	ı	.190
A1	. (80 RE	F
В	.013	-	.023
B1	.013	-	.020
B2	.022	-	.035
С	.007	-	.013
C1	.007	-	.010
D/E	.975	.990	1.000
D1/E1	.920	1	.960
D2/E2	. 8	00 BS	С
D4/E4	. 9	30 BS	C
L	.005	-	-
L1	.020	-	-
L2	.025	-	-
Q	.003	•	1
R	.020	-	.040
N	68		



68-Pin PLCC Package

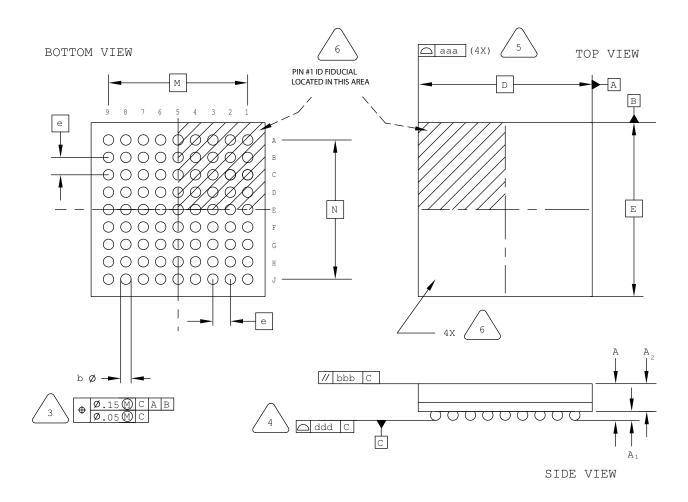
Dimensions in Inches





81-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

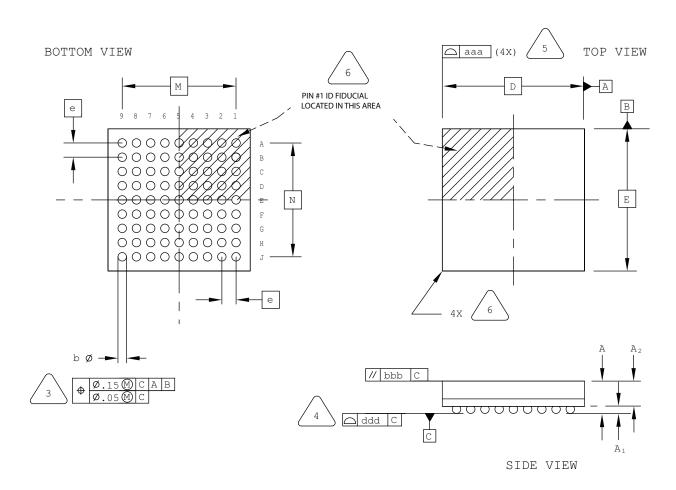


SYMBOL	MIN.	NOM.	MAX.
А	-	ı	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	5.00 BSC		
M/N	4.00 BSC		
b	0.20	0.25	0.30
е	0.50 BSC		
aaa	-	_	0.10
bbb	-	_	0.10
ddd	_	_	0.10



81-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

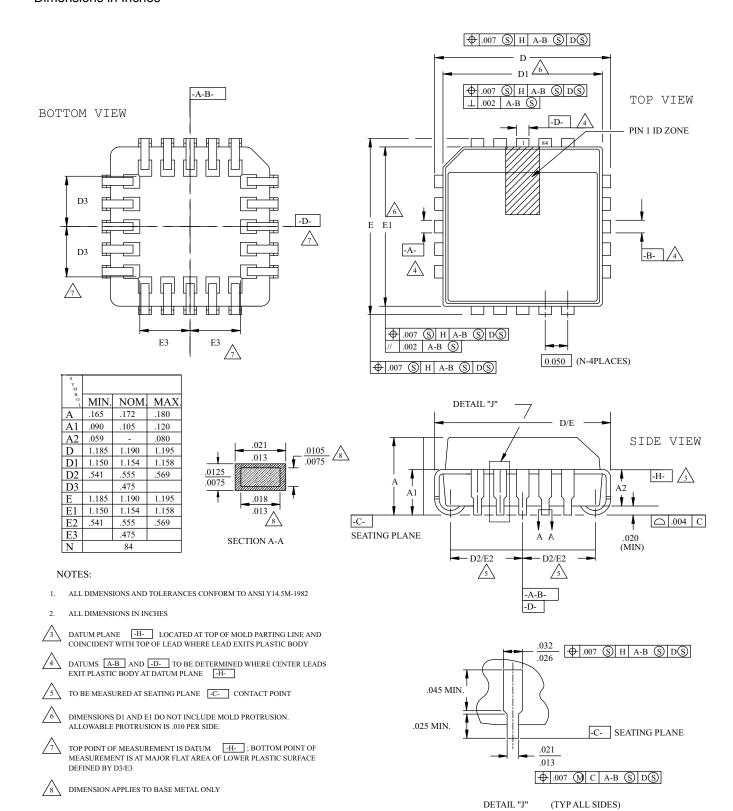


SYMBOL	MIN.	NOM.	MAX.	
А	-	-	1.00	
A1	0.10	_	-	
A2	1	-	0.90	
D/E	4.00 BSC			
M/N	3	3.20 BSC		
b	0.20	0.25	0.30	
е	0	.40 BSC		
aaa	_	_	0.10	
bbb	-	_	0.10	
ddd	-	_	0.10	



84-Pin PLCC Package

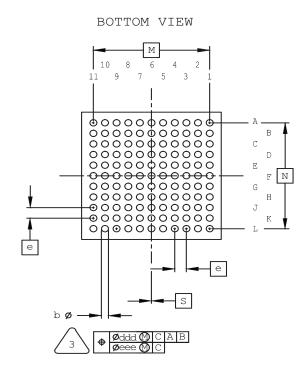
Dimensions in Inches

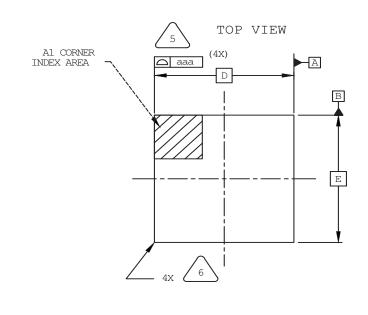


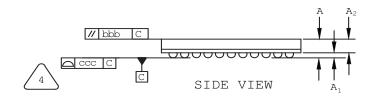


121-Ball csfBGA Package

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM $\overline{\mathbb{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

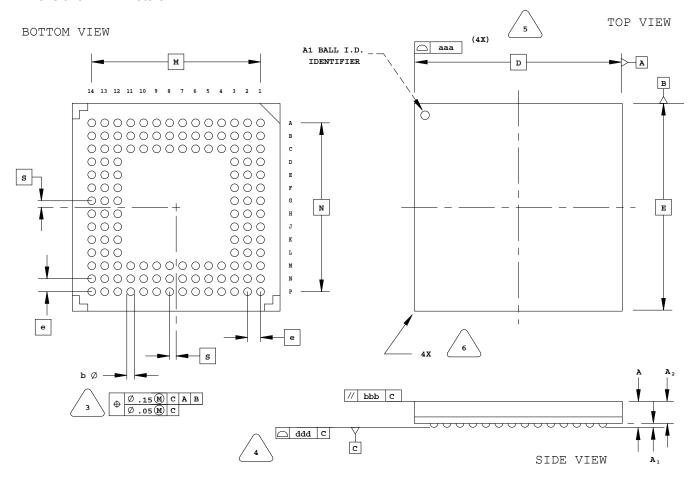


SYMBOL	MIN.	NOM.	MAX.
А	_	_	1.00
A1	0.15	0.24	-
A2	_	0.66	ı
D/E		6.00 BSC	
M/N		5.00 BSC	
S		0.00 BSC	
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee		0.05	



132-Ball csBGA Package Option 1: MachXO2, MachXO, LatticeXP2™

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

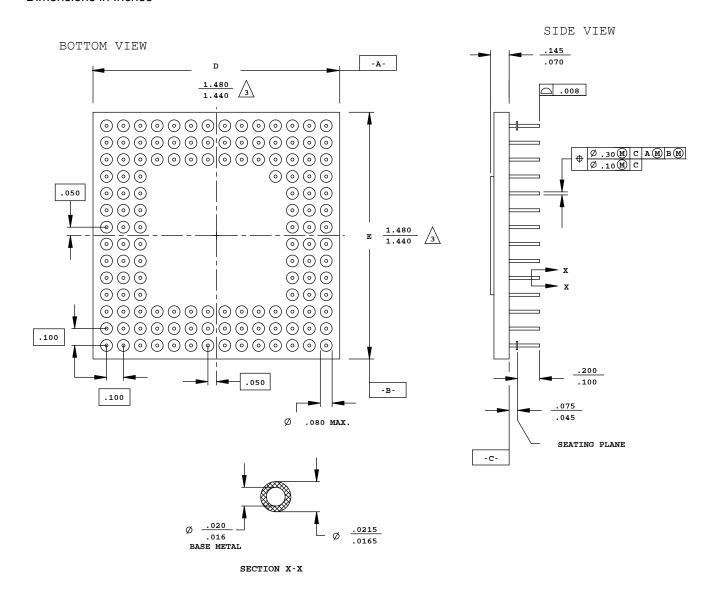


	Г		
SYMBOL	MIN.	NOM.	MAX.
A	0.90	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	8	.00 BSC	
M/N	6.50 BSC		
s	0.	.25 BSC	
b	0.25	0.30	0.35
е	0	.50 BSC	
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08



133-Pin CPGA Package

Dimensions in Inches



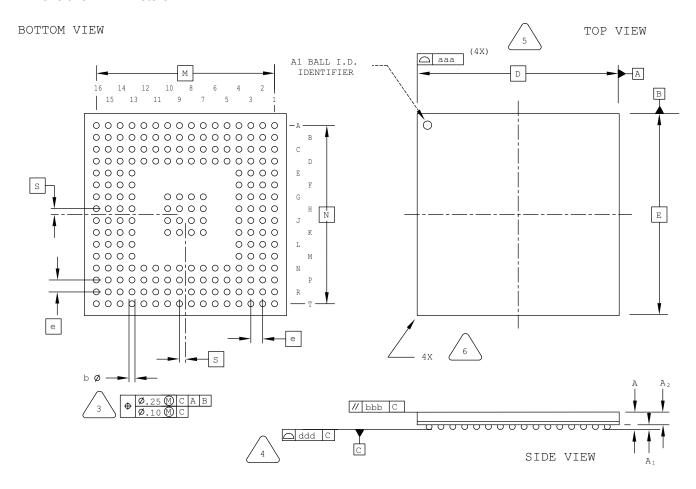
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF
 .006 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN
 NOT TO EXCEED .003 INCHES MAXIMUM PER SIDE.



208-Ball ftBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

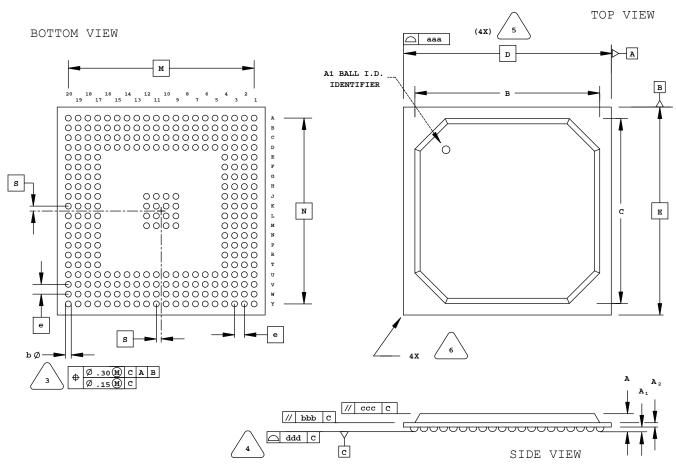


SYMBOL	MIN.	NOM.	MAX.
А	1.25	1.40	1.55
A1	0.30	_	-
A2	_	_	1.25
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0	.50 BSC	
b	0.40	0.50	0.60
е	1.0 BSC		
aaa	-	_	0.20
bbb	_	-	0.25
ddd	_	_	0.12



272-Ball BGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

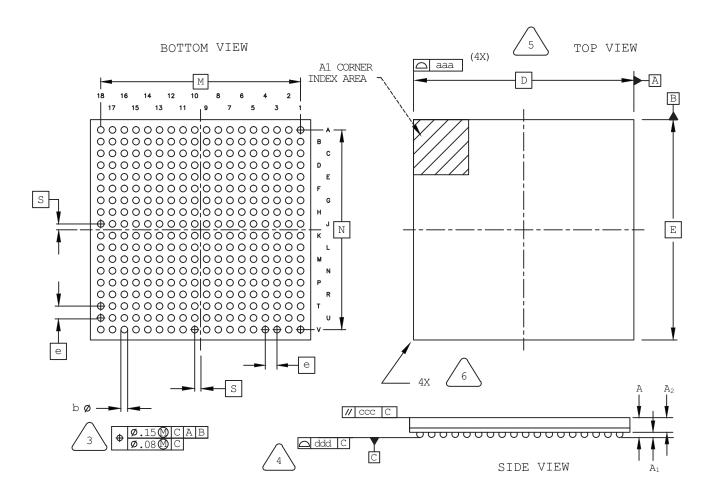


SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.80
A1	0.50	0.65	0.80
A2	0.28	0.54	0.80
B/C	23.80	24.30	24.80
D/E	2	7.00 BSC	
M/N	24	1.13 BSC	
s	0	.635 BSC	
b	0.60	0.75	0.90
е	1	.27 BSC	
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20



324-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

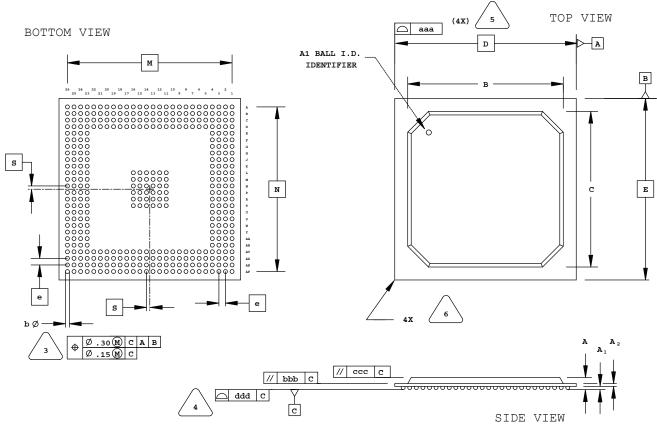


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.70
A1	0.25	0.35	-
A2	0.80	1.00	_
D/E	15.0 BSC		
M/N	13.6 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
е	0.80 BSC		
aaa	_	_	0.15
ccc	_	_	0.20
ddd	_	_	0.20



388-Ball BGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

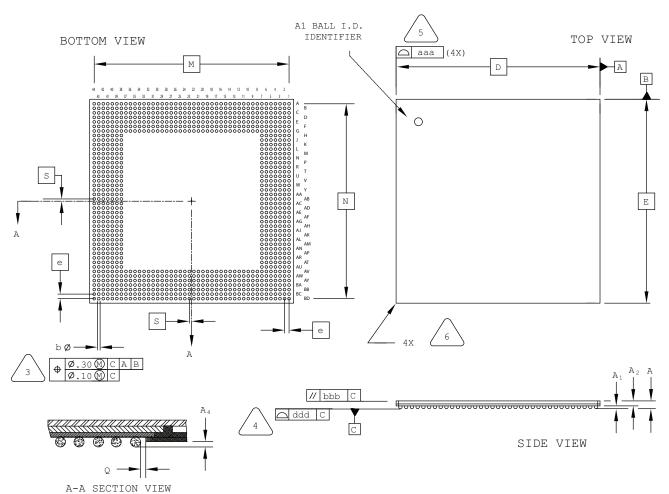


SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.80	3.25
A1	0.50	0.65	0.80
A2	0.28	0.54	0.80
B/C	29.80	31.80	33.80
D/E	35.00 BSC		
M/N	31.75 BSC		
s	0.635 BSC		
b	0.60	0.75	0.90
е	1.27 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20



1036-Ball ftSBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

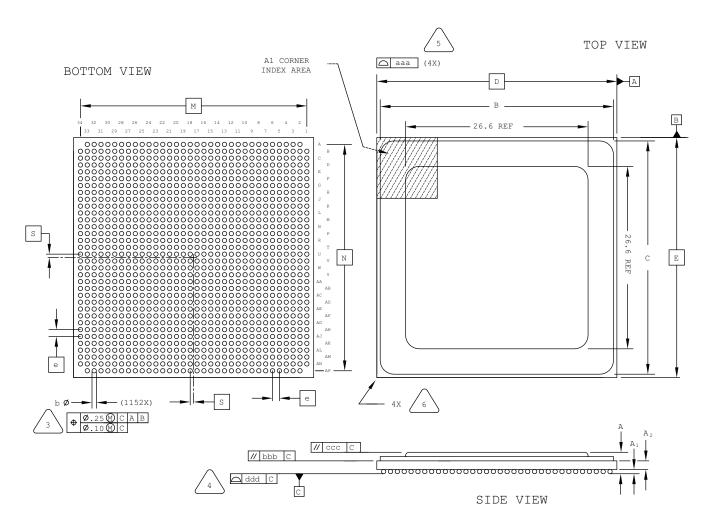


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.80
A1	0.40	0.55	0.70
A2	0.90	0.98	1.10
D/E	45.00 BSC		
M/N	43.00 BSC		
S	0.50 BSC		
b	0.50	0.65	0.80
е	1.00 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.35
ddd	-	-	0.20



1152-Ball Organic fcBGA Package Option 1: LatticeSC/SCM40

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

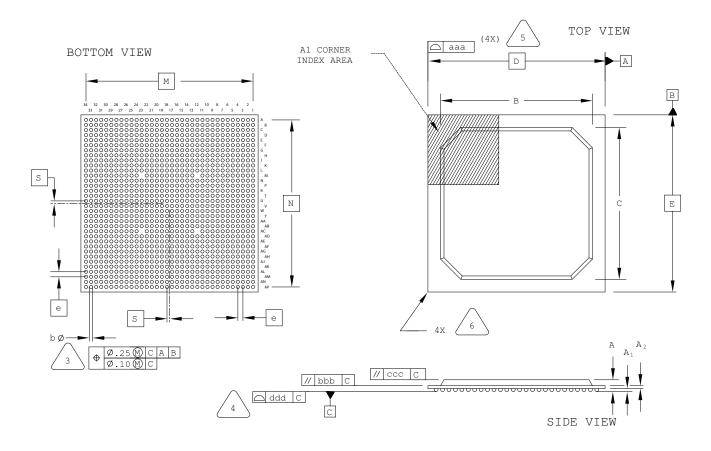


SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.35	0.50	0.65
A2	1.20 REF		
B/C	34.25	34.50	34.75
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	_	_	0.20



1152-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

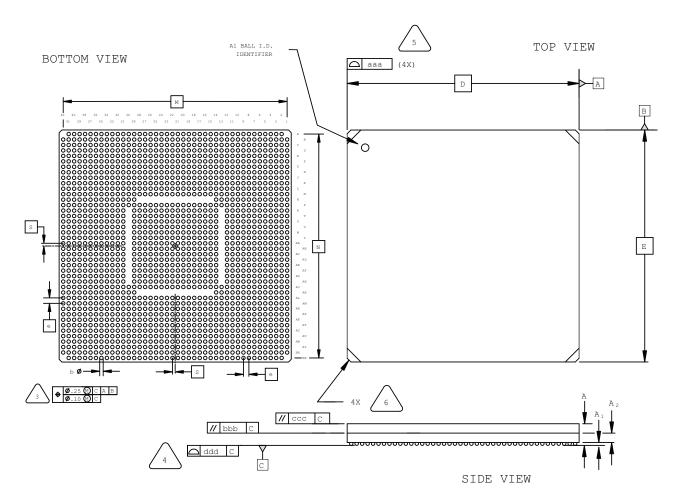
Note: Depopulated ball locations are M12, M23, AC12, and AC23.

SYMBOL	MIN.	NOM.	MAX.
А	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	_	_	0.20
bbb	_	_	0.25
ccc	-	_	0.35
ddd	_	-	0.20



1704-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY. PACKAGE BODY INCLUDES SUBSTRATE AND LID.





SYMBOL	MIN.	NOM.	MAX.
A	4.30	4.80	5.30
A1	0.30	0.50	0.70
A2	1.30	1.60	1.90
D/E	42.50 BSC		
M/N	41.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	1	_	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20